



Material Content Data Sheet



Sales Product Name		TDA5201		Issued		7. September 2015		
MA#		MA000225807						
Package		PG-TSSOP-28-1		Weight*		106.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.077	1.94	1.94	19418	19418
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134620	
	non noble metal	iron	7439-89-6	19.882	18.59	32.05	185904	320524
wire	noble metal	gold	7440-57-5	0.984	0.92	0.92	9197	9197
encapsulation	organic material	carbon black	1333-86-4	0.197	0.18		1844	
	plastics	epoxy resin	-	8.348	7.81		78051	
	inorganic material	silicondioxide	60676-86-0	57.184	53.47	61.46	534684	614579
leadfinish	non noble metal	tin	7440-31-5	1.559	1.46	1.46	14574	14574
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13237	13237
glue	plastics	acrylic resin	-	0.181	0.17		1694	
	noble metal	silver	7440-22-4	0.725	0.68	0.85	6777	8471
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com